



Symposium on Signal Integrity

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Speakers

Dr. Tim Michalka

Topic: Signal Integrity in High-Performance Electrical Design

Dr. Michalka has spent the last 20 years working primarily on the electrical aspects of electronic packaging and interconnections. He has a bachelor's degree in electrical engineering from the University of Maine, a master's and Ph.D. in electrical engineering from Stanford University. He has worked for companies such as Digital Equipment Corporation, Carborundum Microelectronics, and Hewlett-Packard. He has developed power integrity analysis tools and managed a team delivering packaging design and signal integrity solutions for PA RISC microprocessors and custom high-performance ASIC. He is currently with Qualcomm Incorporated, San Diego, CA where he has been a principal engineer and manager of the Power & Signal Integrity Group since 2005. His team works with engineers nationwide to deliver leading edge wireless communications integrated circuits and systems.

Dr. Mohsen Kavehrad

Topic: Toward 100G over Copper

Dr. Kavehrad is the W. L. Weiss (AMERITECH) Endowed Chair Professor of Electrical Engineering at The Pennsylvania State University. He holds a Ph.D. degree in Electrical Engineering from Polytechnic University. After working for companies such as Fairchild Industries, GTE, and Bell Laboratories he joined the Department of Electrical Engineering at the University of Ottawa as a full professor and director of the Broadband Communications Research Laboratory. He later was appointed founding director of the Center for Information and Communications Technology Research (CICTR). He also was the CTO and a vice president at Tele-Beam Inc., State College, PA, and has served as a consultant to major corporations and government agencies.

Dr. Yun Ling, Engineer

Manager, Digital Enterprise Group, Intel Corporation

Topic: Signal Integrity of Complex Systems

Dr. Ling's main responsibility at Intel is to define, develop, and enable high-speed physical interfaces for Intel platforms. His technical areas of expertise include time- and frequency-domain signal integrity modeling and testing, EMC compliance, and thermal/mechanical development. Prior to joining Intel, Dr. Ling worked for AMP, Inc. focusing on contact physics and mechanics research. He earned a Ph.D. in mechanical engineering from SUNY Binghamton. He also taught for six years at Southeast University, China.

Dr. James Drewniak

UMR/MST EMC Laboratory, Missouri University of Science and Technology

Topic: Via Transitions and Stubs at the PCB/Connector Interface: ISI and Jitter Consequences

James L. Drewniak holds a bachelor's, master's, and Ph.D. in electrical engineering from the University of Illinois at Urbana-Champaign. He joined the Electrical Engineering Department at Missouri S & T (formerly the University of Missouri-Rolla) in 1991 and is a faculty member in the Electromagnetic Compatibility Laboratory. His research and teaching interests include electromagnetic compatibility in high-speed digital and mixed-signal designs, signal and power integrity, electronic packaging, electromagnetic compatibility in power electronic based systems, electronics, and antenna design. He has served as the chair of the EMC Society technical committees TC-10 Signal Integrity, and TC-9 Computational Electromagnetics, and is currently an associate editor for the IEEE Transactions on EMC.